

Amendments to the Claims:

This listing of claims will replace the prior version of claims in the application:

Listing of Claims:

1 – 11. (cancelled).

12. (new). A method for bonding a non-metallic substrate to another substrate comprising:

- a) forming a powder adhesive formulation comprising a polymer; wherein said polymer is a natural polymer, a synthetic polymer, or a mixture thereof and wherein said synthetic polymer contains functional monomers and/ or has a glass temperature T_g of between -60 and +40°C;
- b) applying an electrostatic charge to the powder adhesive formulation; and
- c) depositing the charged powder onto a non-metallic substrate, activating said powder adhesive formulation, and contacting the activated adhesive-containing non-metallic substrate with a second substrate;

wherein at least one substrate is paper or plastic, and, when said powder adhesive formulation is activated by heat, the heat being up to 120°C.

13. (new). The method of claim 12 wherein said polymer comprises cationic functionality.
14. (new). The method of claim 12 wherein said substrate is selected from the group consisting of wood, glass, paper, leather, paperboard, card board, corrugated board, cellulose, plastics, wovens, and non-woven materials.
15. (new) The method of claim 12 wherein the steps of step c) are performed in the order of activating the powder adhesive at the same time as it is being deposited onto a non-metallic substrate, then contacting the activated adhesive-containing non-metallic substrate to a second substrate.

16. (new) The method of claim 12 wherein the steps of step c) are performed in the order of depositing the charged powder onto a non-metallic substrate, contacting the adhesive-containing non-metallic substrate, then activating said powder adhesive formulation.
17. (new) The method of claim 12 wherein in step c) the depositing of the charged powder onto a non-metallic substrate is performed in a different manufacturing process than the activation and the contacting the activated adhesive-containing non-metallic substrate with a second substrate.
18. (new). The method of claim 12 wherein said second substrate is a non-metallic substrate.
19. (new). The method of claim 12 wherein said second substrate is a metallic substrate.
20. (new). The method of claim 12 wherein said activation of the powder adhesive comprises contacting the adhesive with a water mist, heat, pH, or radiation.